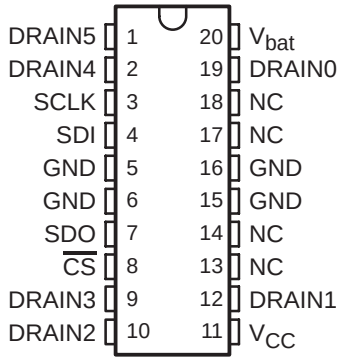
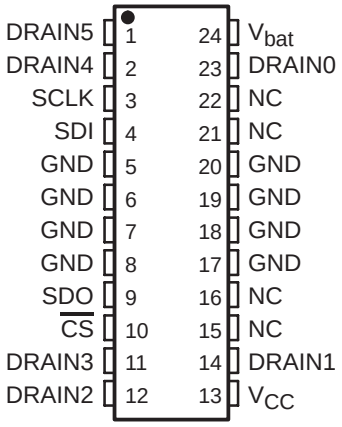
SLIS056A − FEBRUARY 1995 − REVISED MARCH 1996

- **Serial Control With Diagnostics**
- **Six Power DMOS Transistor Outputs of 350-mA Continuous Current**
- **Internal 60-V Inductive Load Clamp**
- **Independent ON-State Shorted-Load/Short-to-Battery Fault Detection on All Drain Terminals**
- **Independent OFF-State Open-Load Fault Sense on All Drain Terminals**
- **Transition of Drain Outputs to Low Duty Cycle Pulsed-Width-Modulation (PWM) Mode for Over-Current Condition**
- **Over-Battery-Voltage-Lockout Protection**
- **Over-Temperature Sense With Serial Interface Fault Status**
- **Fault Diagnostics Returned Through Serial Output Terminal**
- **Internal Power-On Reset of Registers**
- **CMOS Compatible Inputs With Hysteresis**

NE PACKAGE
(TOP VIEW)



DW PACKAGE
(TOP VIEW)



NC − No internal connection

description

The TPIC2603 is a monolithic low-side driver which provides serial interface and diagnostics to control six on-board power DMOS switches. Each channel has independent OFF-state open-load sense, ON-state shorted-load/short-to-battery protection, over-battery-voltage-lockout protection, and over-temperature sense with fault status reported through the serial interface. The device also provides inductive voltage transient protection for each drain output. The TPIC2603 drives inductive and resistive loads such as relays, valves, and lamps.

Serial data input (SDI) is transferred through the serial register when $\overline{CS}$ is low on low-to-high transitions of the serial clock (SCLK). Each string of data must consist of 8 or 16 bits of data. A logic high input data bit turns the respective output channel ON and a logic low data bit turns it OFF. $\overline{CS}$ must be transited high after all of the serial data has been clocked into the device. A low-to-high transition of $\overline{CS}$ transfers the last six bits of serial data to the output buffer, places the serial data out (SDO) terminal in a high-impedance state, and re-enables the fault register. Fault data for the device is sent out the SDO terminal. The first bit of the shift register is exclusively ORed with the fault registers. When a fault exists, the SDI data is inverted as it is transferred out of SDO. Fault data consists of fault flags for over-temperature (bit 6) and shorted/open-load (bits 0-5) for each of the six output channels. Fault register bits are set or cleared asynchronously, when $\overline{CS}$ is high to reflect the current state of the hardware. The fault must be present when $\overline{CS}$ is transited from high to low to be captured and reported in the serial fault data. New faults cannot be captured in the serial register when $\overline{CS}$ is low.

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251−1443

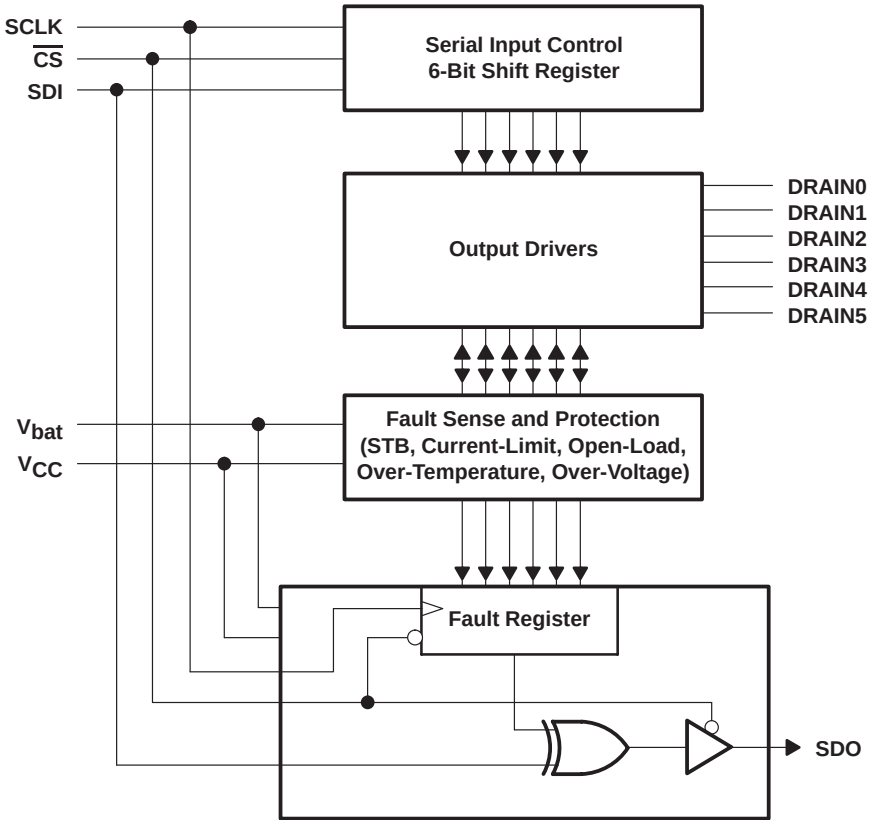
description (continued)

When an over-current or shorted-load fault occurs, the channel transits into a low duty cycle pulse-width-modulated (PWM) signal as long as the fault is present. More detail on fault detection operation is presented in the device operation section of this data sheet.

The TPIC2603 provides pulldown resistors on all active-high inputs except SCLK. A pullup resistor is used on $\overline{CS}$.

The TPIC2603 is characterized for operation over the operating case temperature of −40°C to 125°C.

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.†	I/O	DESCRIPTION
$\overline{CS}$	8 (10)	I	Chip select. The $\overline{CS}$ is an active-low input used to select the serial interface of the device. The device accepts serial input data and transmits fault data when $\overline{CS}$ is held low. An internal pullup resistor is provided on the $\overline{CS}$ input.
DRAIN0 DRAIN1 DRAIN2 DRAIN3 DRAIN4 DRAIN5	19 (23) 12 (14) 10 (12) 9 (11) 2 (2) 1 (1)	O	FET drain outputs. The DRAIN terminals are low-side switches for inductive and resistive loads. Each output provides an internal drain-gate clamp to snub inductive transients.
GND	5, 6, 15, 16 (5, 6, 7, 8, 17, 18, 19, 20)	O	Ground. These terminals provide ground return paths for the device.
SCLK	3 (3)	I	Serial clock. The SCLK clocks the shift register. Serial data is transferred into the SDI port and serial fault data is transferred out of the SDO port of the device on the rising edges of SCLK.
SDI	4 (4)	I	Serial data input. The device receives serial data from the control device using the SDI. Serial input data can be configured in 8-bit or 16-bit data words. Refer to Figures 2 and 4 for input protocol. An internal pulldown resistor is provided on the SDI input.
SDO	7 (9)	O	Serial data output. This 3-state output transfers fault data to the control device after the device has been selected by the $\overline{CS}$ terminal.
V_{bat}	20 (24)	I	Battery voltage. The V_{bat} terminal monitors the battery voltage to detect over-voltage conditions.
V_{CC}	11 (13)	I	Supply voltage. The V_{CC} terminal receives a 5-V supply for internal logic.

† Terminal numbers listed in parenthesis are for the 24-pin DW package.

absolute maximum ratings over the recommended operating case temperature range (unless otherwise noted)‡

Logic supply voltage range, V_{CC} (see Note 1) . . . . . −0.3 V to 7 V
Battery supply voltage range, V_{bat} . . . . . −1.5 V to 60 V
Logic input voltage range, V_I . . . . . −0.3 V to 7 V
Power DMOS drain-to-source voltage, V_{DS} (see Note 2) . . . . . 68 V
Continuous drain current, each output, all outputs on, I_D, T_C = 25°C . . . . . 350 mA
Pulsed drain current, single output, I_{DM}, T_C = 25°C (see Note 3) . . . . . 2.25 A
Single-pusle avalanche energy, E_{AS} (see Figure 11) . . . . . 100 mJ
Continuous total power dissipation . . . . . See Dissipation Rating Table
Avalanche current, I_{AS} (see Note 4) . . . . . 1 A
Operating virtual junction temperature range, T_J . . . . . −40°C to 150°C
Storage temperature range, T_{stg} . . . . . −55°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.
2. Each power DMOS source is internally connected to GND.
3. Pulse duration ≤ 100 µs and duty cycle ≤ 2%.
4. DRAIN supply voltage = 13 V, starting junction temperature (T_{JS}) = 25°C, L = 150 mH, I_{AS} = 1 A (see Figure 11).

DISSIPATION RATING TABLE

PACKAGE	$T_C \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_C = 25°C$	$T_C = 125°C$ POWER RATING
DW	1750 mW	14 mW/°C	350 mW
NE	2500 mW	20 mW/°C	500 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Logic supply voltage, V_{CC}	4.5	5	5.5	V
Battery supply voltage, V_{bat}	5.5	12	25	V
High-level input voltage, V_{IH}	0.7 V_{CC}		V_{CC}	V
Low-level input voltage, V_{IL}	0		0.3 V_{CC}	V
Operating case temperature, T_C	−40		125	°C

electrical characteristics, T_C = −40°C to 125°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V_{bat}	Battery supply voltage	Normal operation			5.5		25	V
I_{bat}	Battery supply current	V_{CC} = 5 V					5	mA
		V_{CC} = 0					50	µA
V_{CC}	Logic supply voltage				4.5		5.5	V
I_{CC}	Logic supply current	All outputs off,	V_{bat} = 5.5 V				5	mA
$V_{(turn-on)}$	V_{CC} turn-on voltage (logic operational)	V_{bat} = 5.5 V,	Check output functionality				4.5	V
$V_{(ov)}$	Over-battery voltage shutdown	Gate disabled			30		38	V
$V_{hys(ov)}$	Over-battery voltage reset hysteresis				0.4		2	V
$r_{DS(on)}$	Drain-to-source on-state resistance	V_{bat} = 13 V	I_O = 0.35 A,	T_C = 25°C		0.7	1	Ω
		V_{bat} = 5.5 V				1.7	2.3	
		V_{bat} = 13 V	I_O = 0.35 A,	T_C = 125°C		1.2	1.7	
		V_{bat} = 5.5 V				2.7	3.8	
I_L	On-state current limit				0.8	2	5	A
$I_{L(sense)}$	Over-current sense				0.8	1.5	3	A
I_{IH}	Input pullup current	GND < V_I < 0.7 V_{CC},	$\overline{CS}$ input only		−5	−10	−50	µA
I_{IL}	Input pulldown current	0.3 V_{CC} < V_I < V_{CC},	All other inputs		2.5	10	25	µA
$I_{D(off)}$	Off-state drain current	V_{load} = V_{bat} = 14.5 V			20	40	80	µA
$I_{O(sleep)}$	Sleep-state output current	V_{bat} < 0.5 V,	V_{CC} < 0.5 V,	Load = 14 V			50	µA
V_{OH}	High-level serial output voltage	I_O = 1 mA			0.8 V_{CC}			V
V_{OL}	Low-level serial output voltage	I_O = 1 mA				0.2	0.4	V
I_{OZ}	High impedance state output current	V_{CC} = 5.5 V to 0 V,	SDO output		−10	1	10	µA
$V_{(BR)DSX}$	Drain-to-source breakdown voltage	dc < 1%,	t_w = 100 µs,	I_O = 20 mA	52	58	68	V
$T_{j(sense)}$	Thermal flag				150	170	185	°C
$T_{j(hys)}$	Thermal flag hysteresis				5	10	15	°C
$V_{(open)}$	Open-load detection voltage				0.3 V_{CC}		0.7 V_{CC}	V

switching characteristics, V_{CC} = 5 V, T_C = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_w	Clock cycle period pulse duration, SCLK	See Figure 1		250	555	ns
$t_{wH(SCLK)}$	Pulse duration, SCLK high	See Figure 1		100	248	ns
$t_{wL(SCLK)}$	Pulse duration, SCLK low	See Figure 1		100	248	ns
t_{pd1}	Propagation delay from falling edge of $\overline{CS}$ to SDO valid	$\overline{CS}$ = 0.8 V to SDO low impedance (see Figure 1)		150	300	ns
t_{pd2}	Propagation delay from rising edge of $\overline{CS}$ to SDO 3-state	$\overline{CS}$ = 2 V to SDO 3-state		150	200	ns
t_{pd3}	Propagation delay from SCLK to SDO valid	$\overline{CS}$ < 0.8 V		80	172	ns
$t_{r(SDO)}$	Rise time of SDO	C_{load} = 200 pF		30	50	ns
$t_{f(SDO)}$	Fall time of SDO	C_{load} = 200 pF		30	50	ns
$t_{(stb)}$	Short-to-battery/shorted-load/open-load deglitch time	See Figures 5 and 6	25	70	100	µs
$t_{d(on)}$	Turn-on delay time, rising edge of $\overline{CS}$ to drain	V_{bat} = 14 V, R_{load} = 30 Ω	0.4	5	10	µs
$t_{d(off)}$	Turn-off delay time, rising edge of $\overline{CS}$ to drain		0.4	5	15	
$t_{r(drain)}$	Rise time of drain terminal		0.4	5	10	
$t_{f(drain)}$	Fall time of drain terminal		0.4	5	10	
$f_{(SCLK)}$	Serial clock frequency		1.8	4		MHz
$t_{cyc(ref)}$	Short-to-battery sense cycle time	See Figure 5	1.6	4	6.4	ms
$t_{w(sense)}$	Short-to-battery sense pulse duration	See Figure 5	25	70	100	µs
t_{su1}	Setup to/from the fall edge of $\overline{CS}$ to the rising edge of SCLK	See Figure 1		150	200	ns
$t_{su(SDI)}$	Setup time, SDI to SCLK	See Figure 1		25	55	ns
$t_{h(SDI)}$	Hold time, SDI after SCLK	See Figure 1		10	55	ns

thermal resistance

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	All outputs with equal power		50	°C
$R_{\theta JC}$	Junction-to-case thermal resistance	All outputs with equal power		10	°C

PRINCIPLES OF OPERATION

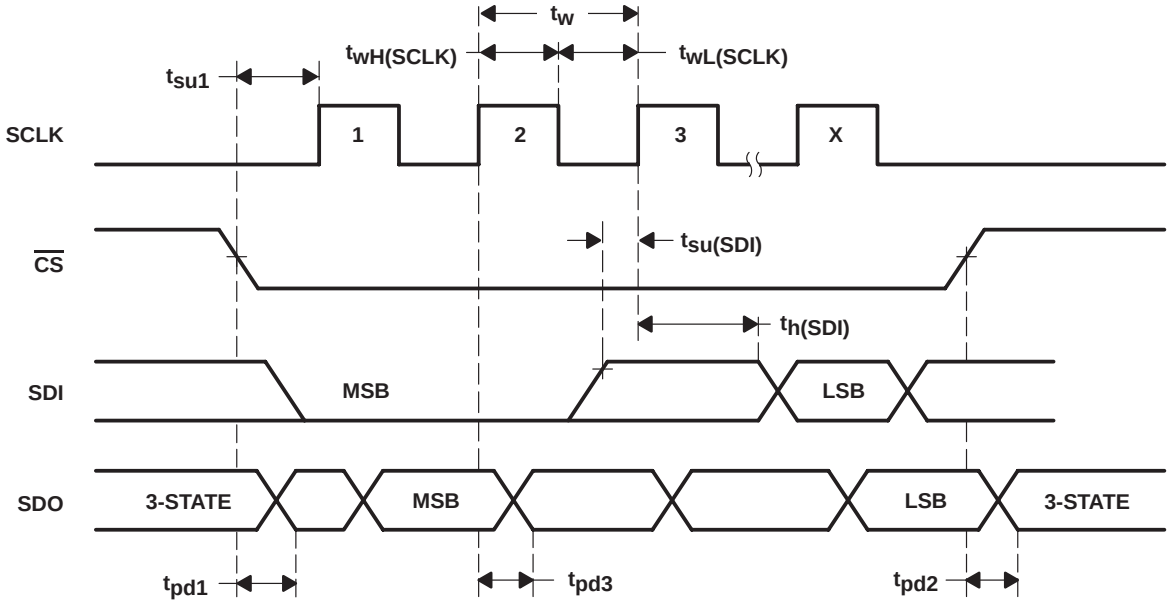


Figure 1. Switching Characteristics

serial interface

Control information is transferred into the TPIC2603 through the serial interface. The serial interface consists of a serial clock (SCLK), chip select ($\overline{CS}$), serial data input (SDI), and serial data output (SDO). Serial data is shifted, most significant bit (MSB) first, into the SDI shift register on the rising edge of the first SCLK after $\overline{CS}$ has transited from high to low. The controller must shift either eight bits or sixteen bits of data into the device with the last six bits of input data containing control information for the output drivers. Data bits preceeding the output control information should be set to 0. A low-to-high transition on $\overline{CS}$ latches the contents of the last six bits of the serial shift register into the output buffer. A low input to SDI turns the corresponding parallel output OFF and a high input will turn the output ON (see Figure 2).

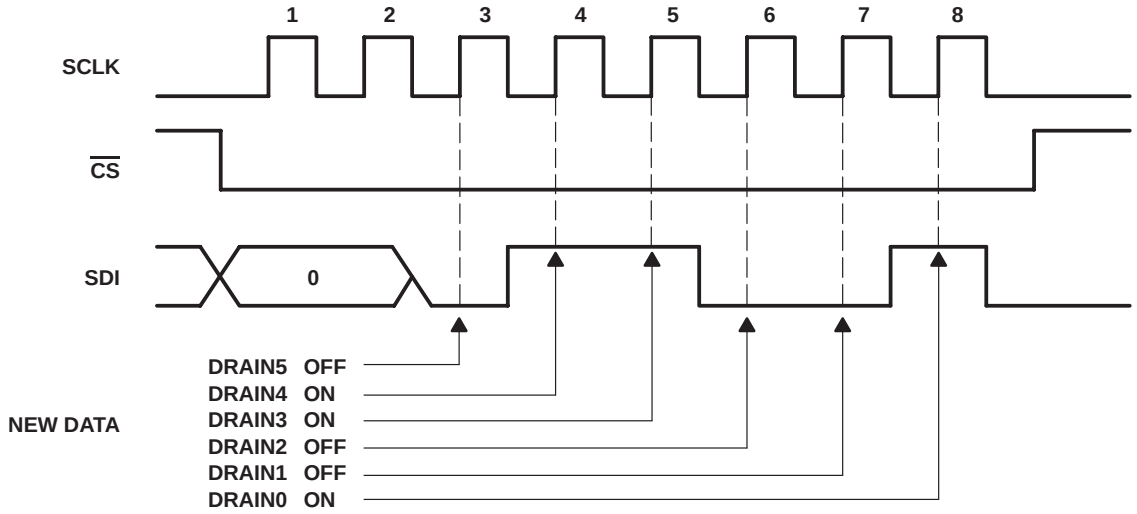


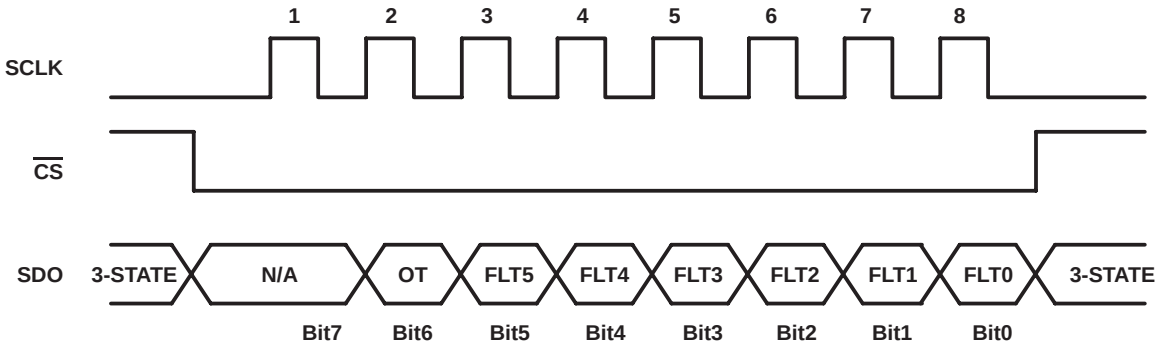
Figure 2. Serial Input Control

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251−1443

PRINCIPLES OF OPERATION

serial interface (continued)

Fault isolation data for each channel and global over-temperature status is transferred to the control device using the serial interface. Fault status for the TPIC2603 is captured as $\overline{CS}$ transits low. The fault interface monitors the SDI terminal and exclusively ORs the respective input control bit with the corresponding fault information bit stored in the fault register. Each exclusive ORed fault bit is transferred out the SDO terminal on the rising edge of the SCLK. Serial data can be transferred in 8-bit or 16-bit words as illustrated in Figure 4, with fault data appearing in the first 8-bits of serial output data. The $\overline{CS}$ must be transited high after the serial transfer has completely latched the new control data into the output control buffer and re-enable fault reporting on the device (see Figures 3 and 4).



NA = Unused
OT = Over-temperature fault bit
FLT5 = Shorted or open-load fault on channel 5
FLT4 = Shorted or open-load fault on channel 4
FLT3 = Shorted or open-load fault on channel 3
FLT2 = Shorted or open-load fault on channel 2
FLT1 = Shorted or open-load fault on channel 1
FLT0 = Shorted or open-load fault on channel 0

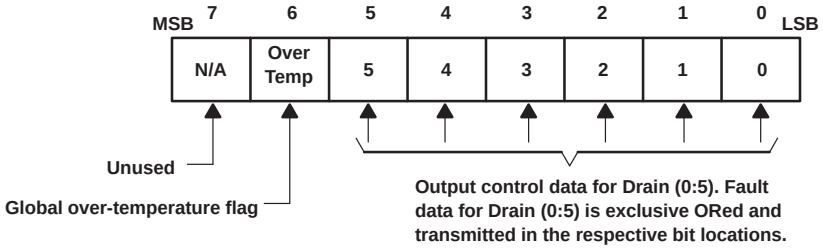
NOTE A: MSB is the first bit transferred.

Figure 3. Serial Output Control

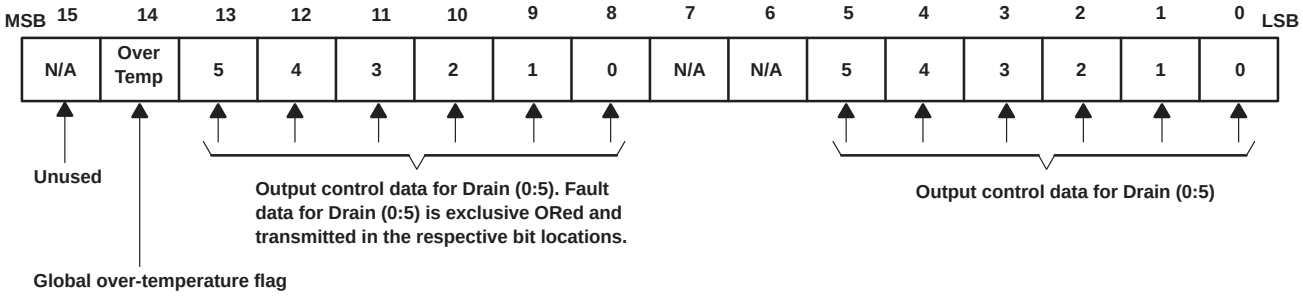
PRINCIPLES OF OPERATION

serial interface (continued)

Serial I/O Protocol (8-Bit Configuration)



Serial I/O Protocol (16-Bit Configuration)



NOTE A: MSB is the first bit transferred.

Figure 4. Serial Data Fault Protocol

PRINCIPLES OF OPERATION

fault sense/protection circuitry

over-current/short-to-battery sensing and protection

The internal fault protection circuitry of the TPIC2603 monitors the drain current for each channel. Each channel offers two levels of protection from over-current conditions. The first level is a current-limit protection which through the internal FET prevents the switching current from exceeding the on-state current limit. The second level of protection transits the output to a low duty cycle PWM mode when the current exceeds the over-current sense threshold. The PWM mode protection is enabled approximately 70 μs after the output has been turned on. The output remains in the PWM mode until the shorted-load condition has been corrected and then automatically returns to normal operation. Figure 5 illustrates device operation under an over-current or shorted-load condition.

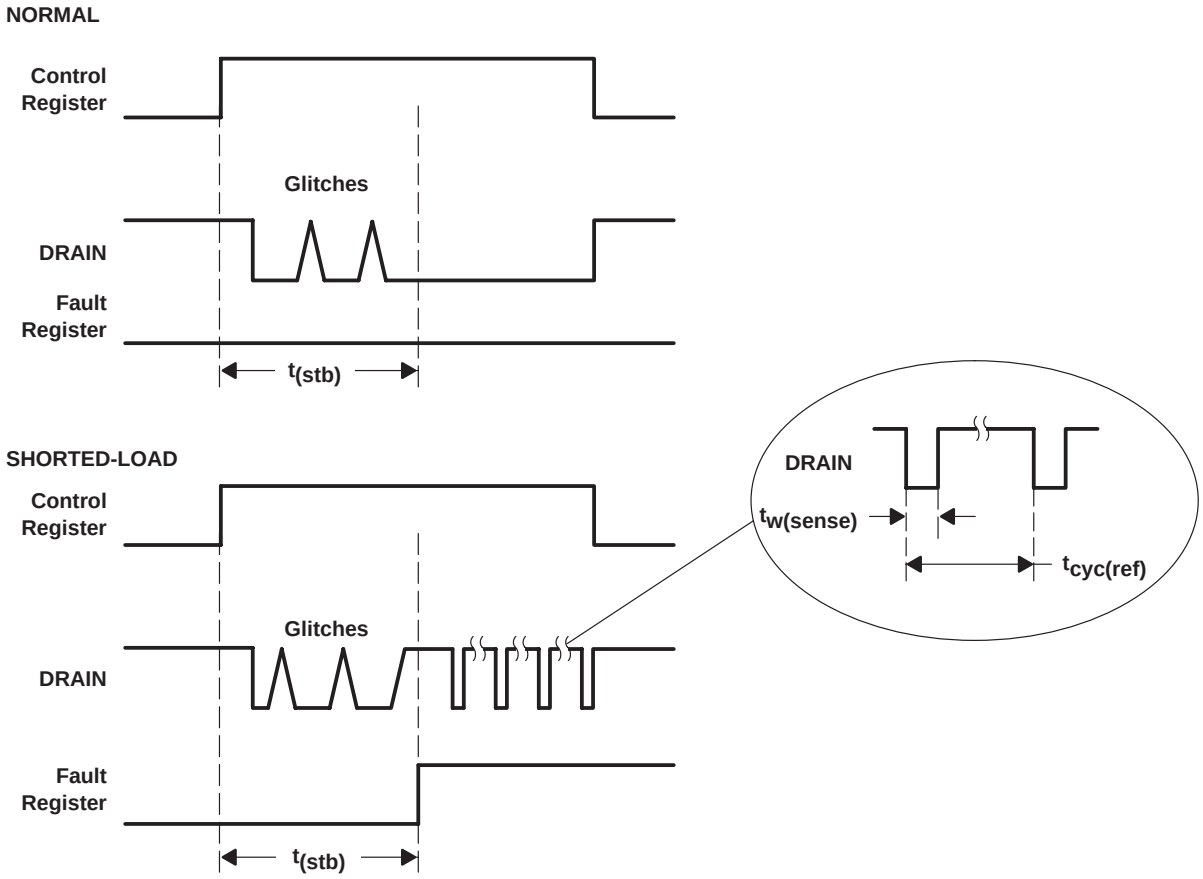


Figure 5. Shorted-Load Condition

PRINCIPLES OF OPERATION

open-load/short-to-ground sensing

The TPIC2603 checks for open-load and short-to-ground conditions when the output is turned OFF. When the output turns OFF, a 40-μA current source switches onto the drain. Under normal conditions, the load provides adequate current to overcome the current source and the drain voltage remains above the open-load detection threshold. When the output is open, then the current source pulls the drain low and an open-load condition is flagged. The open-load test is enabled approximately 70 μs after the output turns OFF to allow the drain to stabilize. Figure 6 illustrates device operation under open-load conditions.

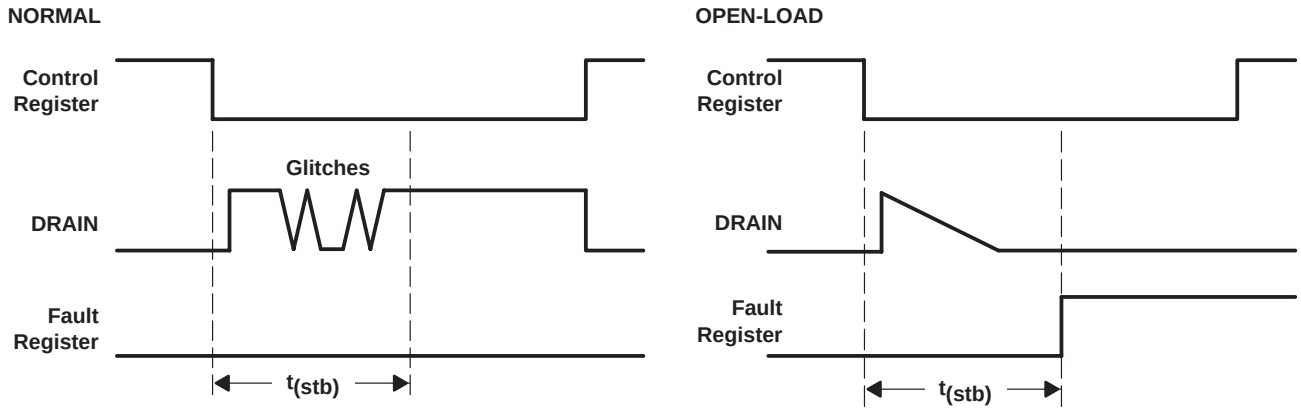


Figure 6. Open-Load Condition

over-voltage sensing and protection

The TPIC2603 monitors the V_{bat} input terminal to protect the device and load from over-battery voltage conditions. The device disables all of the drain outputs when V_{bat} goes above 35 V. An over-battery voltage hysteresis is provided to prevent the outputs from transiting ON and OFF erratically near the over-voltage threshold. The device automatically returns to normal operation after the over-voltage condition has been corrected. Figure 7 illustrates device operation under an over-battery voltage condition.

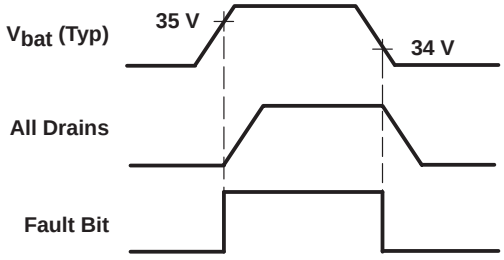


Figure 7. Over-Battery Voltage Condition

PRINCIPLES OF OPERATION

over-temperature sensing

The TPIC2603 monitors the junction temperature of the die to detect over-temperature conditions which may damage the device. When the junction temperature goes above approximately 170°C, the fault logic sets the global over-temperature fault bit. An over-temperature fault is reported using the serial interface on bit 6 (for 8-bit configuration) or bit 14 (for 16-bit configuration). The global over-temperature fault output in the serial data is exclusively ORed with the second bit (bit 6 for 8-bit configuration or bit 14 for 16-bit configuration) of data input to the SDI terminal. Bit 6 or bit 14 of the input data should be set low. Over-temperature faults are for informational purposes only and do not affect the state of the drains. Figure 8 illustrates device operation under over-temperature conditions.

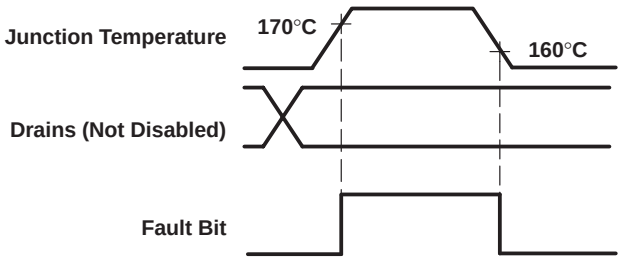
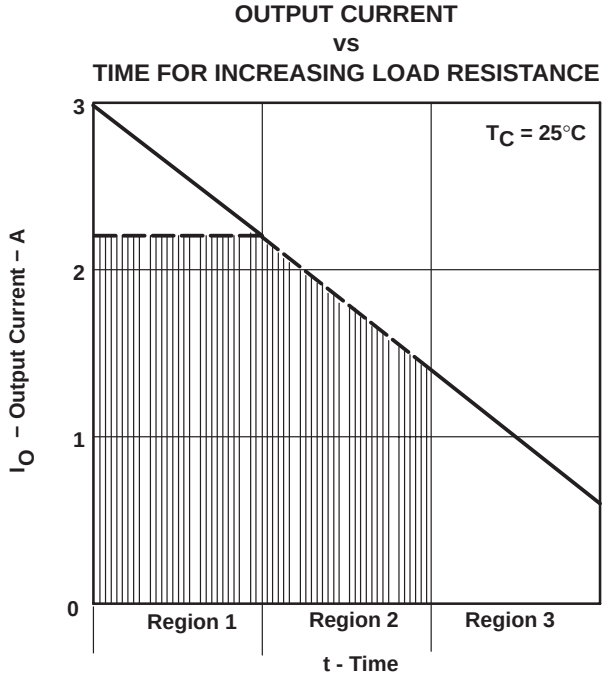
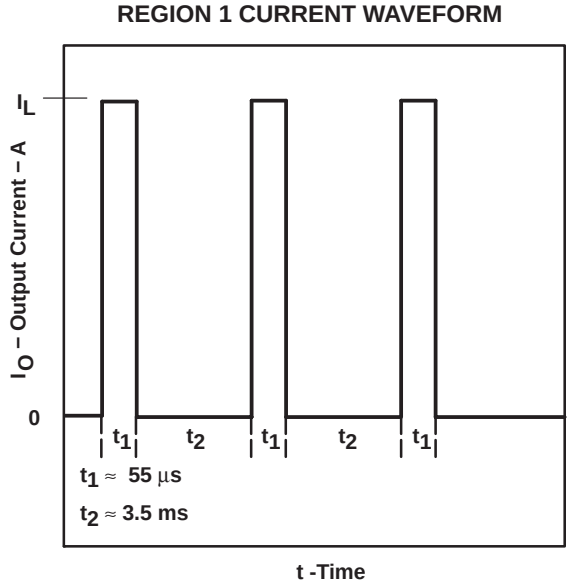


Figure 8. Over-Temperature Sense

PARAMETER MEASUREMENT INFORMATION





First output current pulses after turn-on in chopping mode with resistive load.

NOTES: A. Region 1 − Analog current limit holds the maximum current while the device runs in chop mode.
B. Region 2 − Analog current limit is removed but device continues in chop mode.
C. Region 3 − Current is below chop mode sense; therefore, it is in normal operation. Variable load is resistance over time.

Figure 9. Chopping-Mode Characteristics

PARAMETER MEASUREMENT INFORMATION

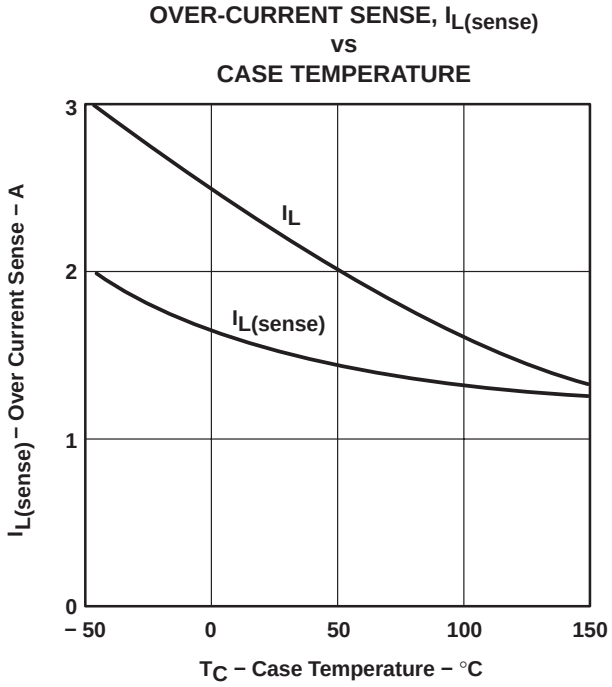
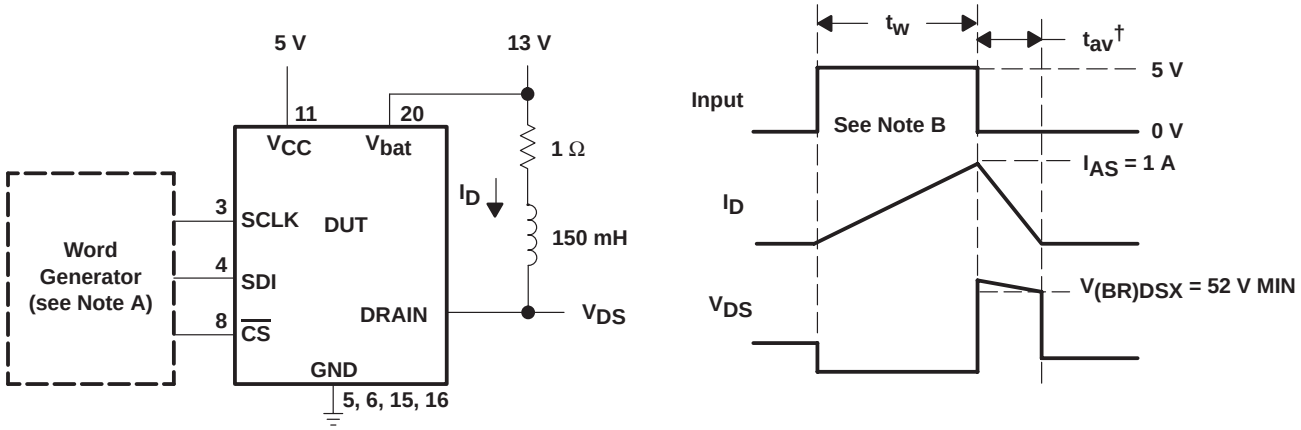


Figure 10



Pinout for NE Package Shown

SINGLE-PULSE AVALANCHE ENERGY TEST CIRCUIT **VOLTAGE AND CURRENT WAVEFORMS**

† Non-JEDEC symbol for avalanche time.

NOTES: A. The word generator has the following characteristics: $t_r \le 10$ ns, $t_f \le 10$ ns, $Z_O = 50\ \Omega$.

B. Input pulse duration, t_W, is increased until peak current $I_{AS} = 1$ A.
Energy test level is defined as $E_{AS} = (I_{AS} \times V_{(BR)DSX} \times t_{av})/2 = 100$ mJ.

Figure 11. Single-Pulse Avalanche Energy Test Circuit and Waveforms

TYPICAL CHARACTERISTICS

MAXIMUM CONTINUOUS DRAIN CURRENT OF EACH OUTPUT vs NUMBER OF OUTPUTS CONDUCTING SIMULTANEOUSLY

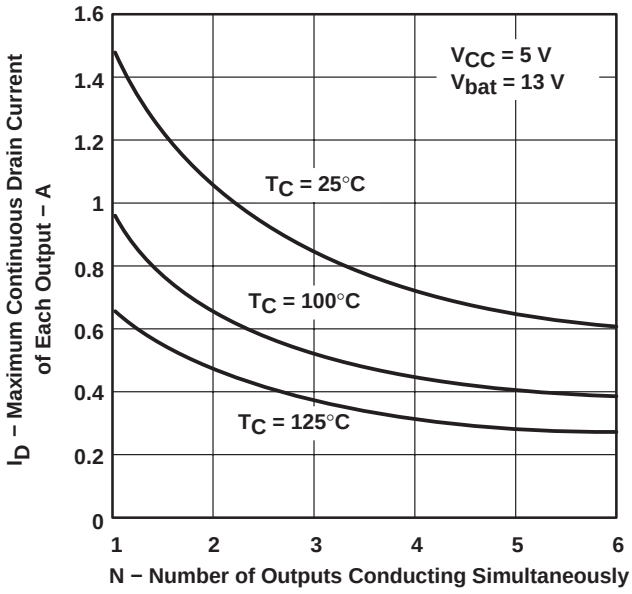


Figure 12

MAXIMUM PEAK DRAIN CURRENT OF EACH OUTPUT vs NUMBER OF OUTPUTS CONDUCTING SIMULTANEOUSLY

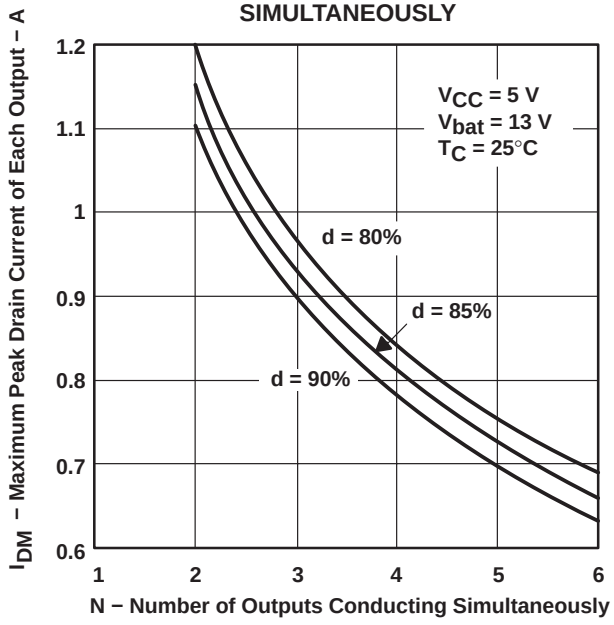
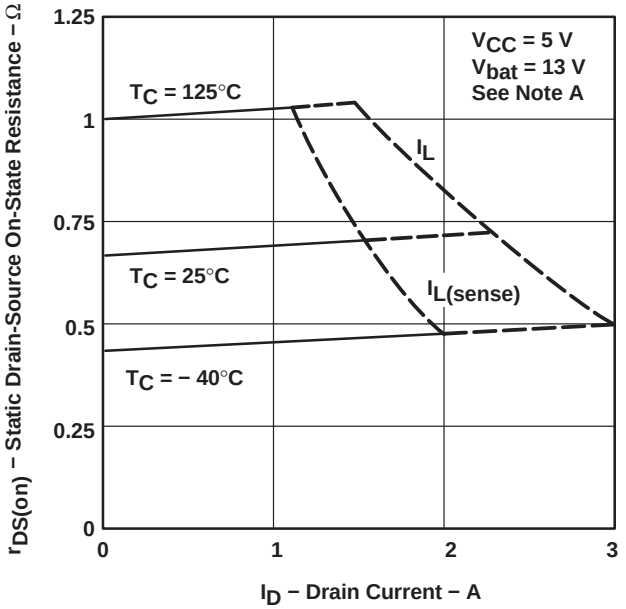


Figure 13

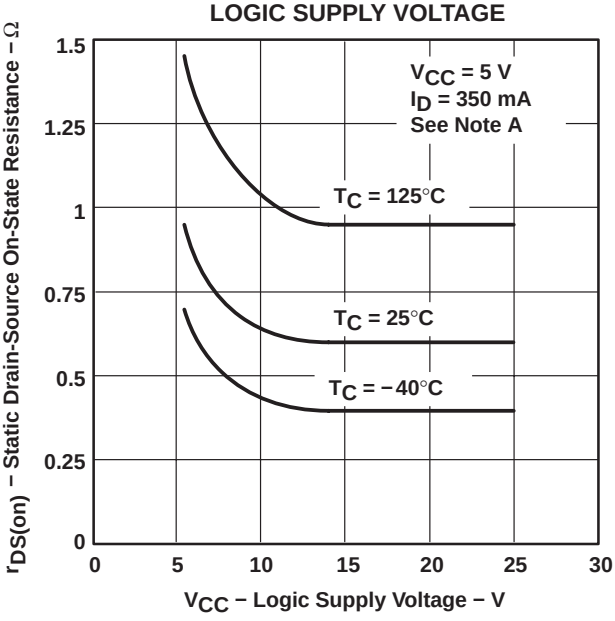
STATIC DRAIN-SOURCE ON-STATE RESISTANCE vs DRAIN CURRENT



NOTE A: Technique should limit $T_J - T_C$ to 10°C maximum.

Figure 14

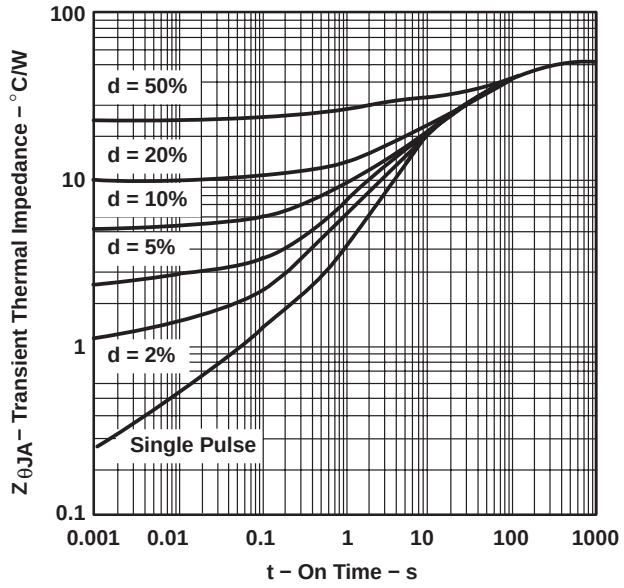
STATIC DRAIN-SOURCE ON-STATE RESISTANCE vs LOGIC SUPPLY VOLTAGE



NOTE A: Technique should limit $T_J - T_C$ to 10°C maximum.

Figure 15

THERMAL INFORMATION



The single-pulse curve represents measured data. The curves for various pulse durations are based on the following equation:

$$Z_{\theta JA} = \left|\frac{t_w}{t_c}\right| R_{\theta JA} + \left|1 - \frac{t_w}{t_c}\right| Z_\theta(t_w + t_c) + Z_\theta(t_w) - Z_\theta(t_c)$$

Where:

$Z_\theta(t_w)$ = the single-pulse thermal impedance for t = t_w seconds

$Z_\theta(t_c)$ = the single-pulse thermal impedance for t = t_c seconds

$Z_\theta(t_w + t_c)$ = the single-pulse thermal impedance for t = $t_w + t_c$ seconds

$d = t_w/t_c$

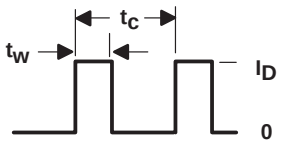


Figure 16

TEXAS INSTRUMENTS
POST OFFICE BOX 655303 • DALLAS, TEXAS 75265
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251−1443

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TPIC2603DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPIC2603DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPIC2603DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPIC2603DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPIC2603NE	OBSOLETE	PDIP	NE	20		TBD	Call TI	Call TI	

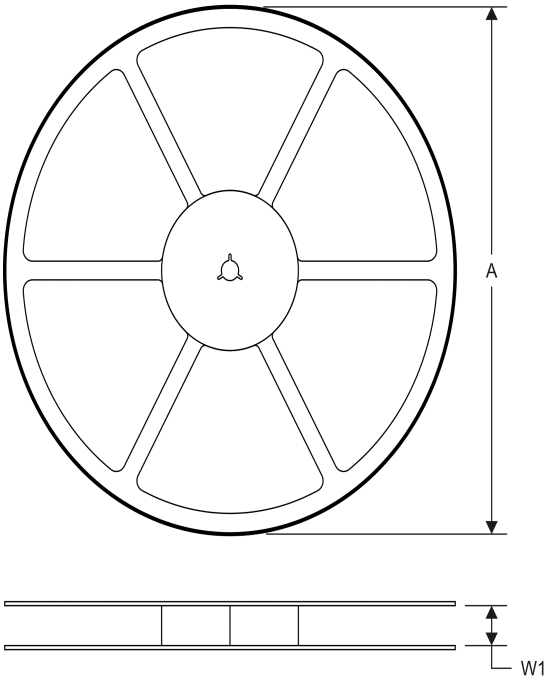
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

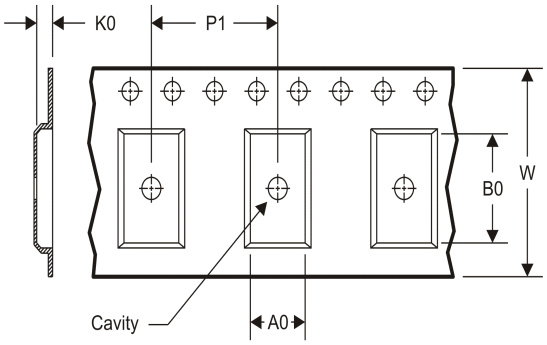
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



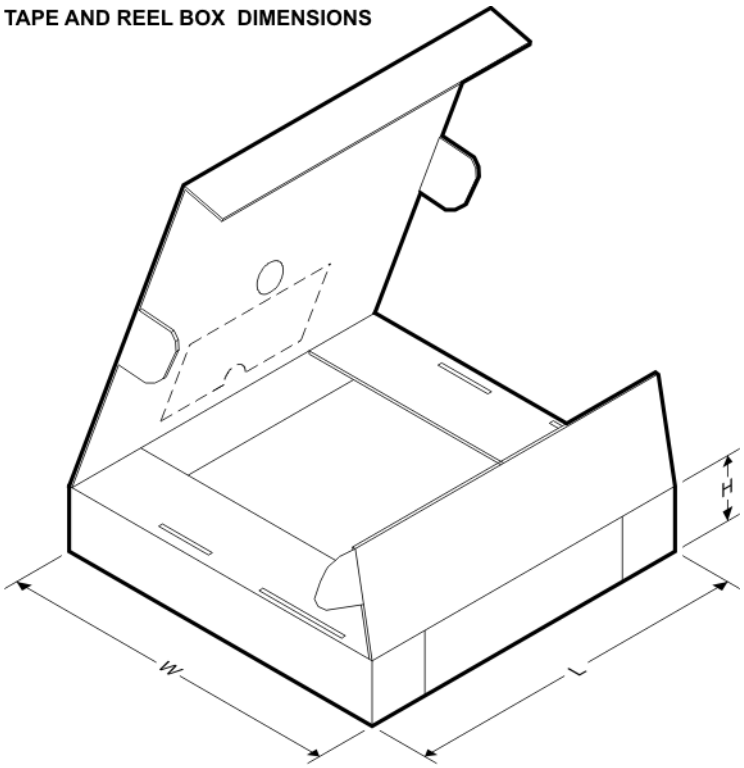
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPIC2603DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

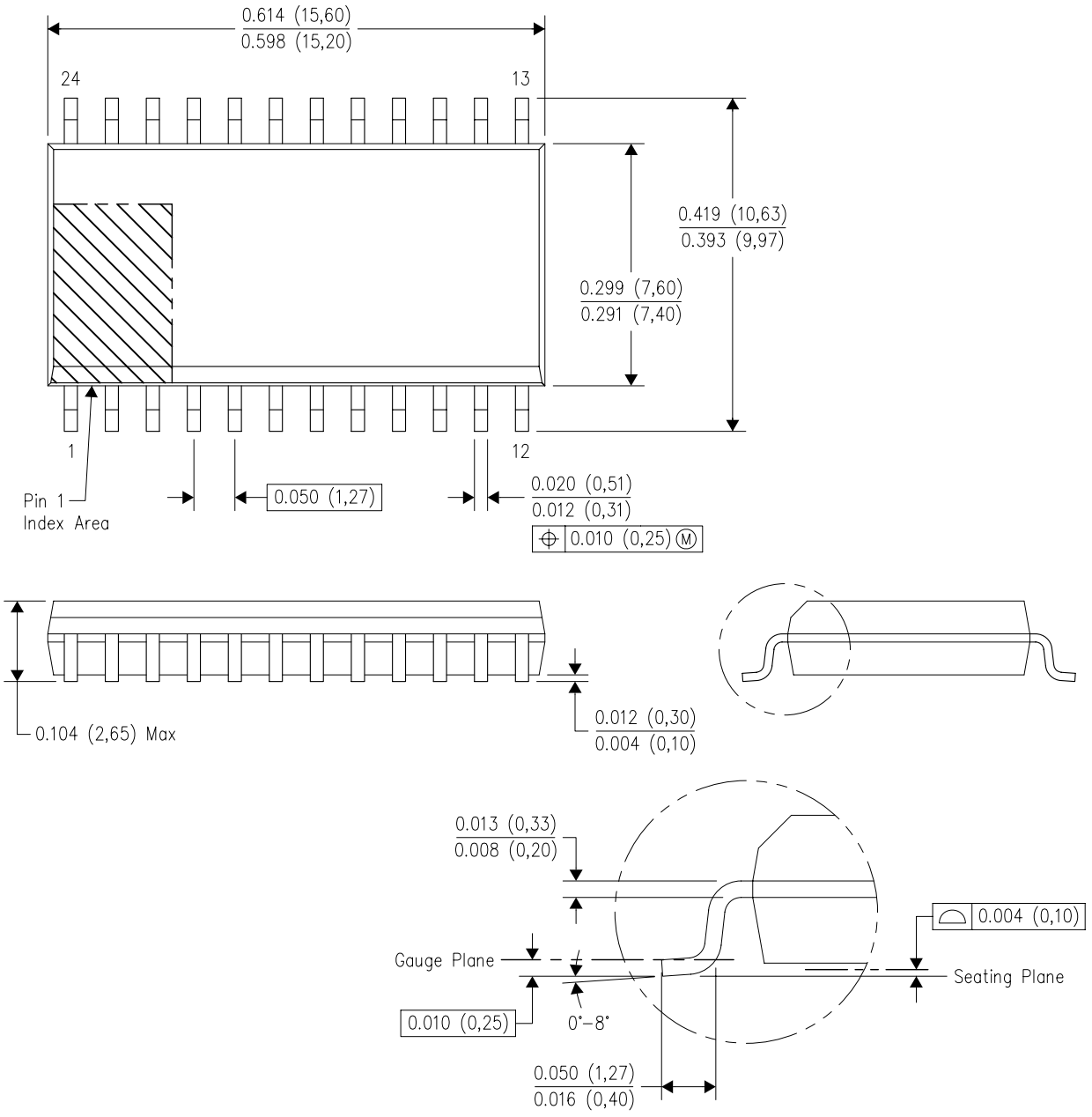
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPIC2603DWR	SOIC	DW	24	2000	367.0	367.0	45.0

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265